electronic equipment, the heat as a causative factor is a major problem. Thus, there has been an increase in demand for a highly thermally conductive adhesive that conducts heat evolved from electronic parts without loss from the parts and circuit boards to the housing and heat sinks.

[0003]

As a material used for the highly thermally conductive adhesive, a resin composition prepared by adding high heat dissipation inorganic filler to a thermosetting resin such as an epoxy resin to increase the thermal conductivity has been proposed (See, for example, Patent Literature 1 and 2). Moreover, with regard to adhesives containing a polyimide resin or a polyimide silicone resin, an adhesive composition improved in thermal conductivity, heat resistance and adhesive properties by addition of high heat dissipation inorganic filler has been proposed (See, for example, Patent Literatures 3, 4 and 54).

Citation List

Patent Literature

[0004]

Patent Literature 1: Japanese Patent Laid-Open No. 2008-266378

Patent Literature 2: Japanese Patent Laid-Open No. 2009-292881

Patent Literature 3: Japanese Patent Laid-Open No. 2010-84072

Patent Literature 4: Japanese Patent Laid-Open No. 2005-113059

Patent Literature 5: United States Patent Publication No. 2007/098995.

Summary of Invention

Technical Problem

[0005]

However, there are problems such that when an inorganic filler is incorporated into the conventional composition in large quantities, the thermal conductivity is not significantly enhanced because the dispersibility of the filler in resins deteriorates, and the toughness and adhesive properties are remarkably lowered.

[0006]

Thus, an object of the present invention is to provide an adhesive composition being capable of controlling the dispersibility of a thermally conductive filler, having high thermal conductivity and being excellent in adhesion to heating elements and heat sink materials.

Solution to Problem

[0007]

In order to solve the above-mentioned problems, the present invention is directed to an adhesive composition

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